

SECTION 1 - SERVICING

1. Preventive Maintenance Procedures

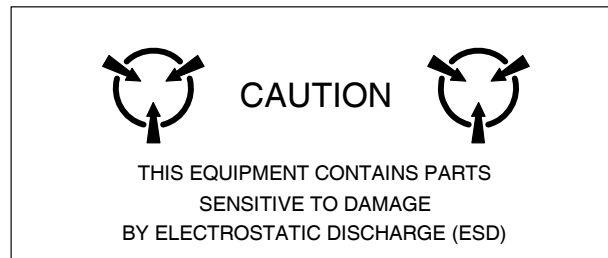
Contains routine maintenance instructions for cleaning and inspecting the Test Set.

CAUTION: DISCONNECT POWER FROM TEST SET TO AVOID POSSIBLE DAMAGE TO ELECTRONIC CIRCUITS.

A. External Cleaning

STEP	PROCEDURE
1.	Clean front panel and display face with soft lint-free cloth. If dirt is difficult to remove, dampen cloth with water and mild liquid detergent.
2.	Remove grease, fungus and ground-in dirt from surfaces with soft lint-free cloth dampened (not soaked) with isopropyl alcohol.
3.	Remove dust and dirt from connectors with soft-bristled brush.
4.	Cover connectors, not in use, with suitable dust cover to prevent tarnishing of connector contacts.
5.	Clean cables with soft lint-free cloth.
6.	Paint exposed metal surface to avoid corrosion.

B. Internal Cleaning



CAUTION: DO NOT MOVE COMPONENTS ON CIRCUIT BOARDS OR DISASSEMBLE CONNECTORS NEEDLESSLY TO AVOID POSSIBLE DAMAGE.

CAUTION: DO NOT OPEN COMPLEX INTERNAL MODULES FOR SOLE PURPOSE OF CLEANING AND INSPECTION.

Remove dust with hand-controlled dry air jet of 15 psi (1.054 kg/cm²) and wipe internal chassis parts and frame with soft lint-free cloth moistened with isopropyl alcohol.

C. Visual Inspection

STEP	PROCEDURE
1. Inspect Chassis for:	<ul style="list-style-type: none"> ● Tightness of sub-assemblies and chassis mounted connectors. ● Corrosion or damage to metal surfaces.
2. Inspect Capacitors for:	<ul style="list-style-type: none"> ● Loose mounting, deformities or obvious physical damage. ● Leakage or corrosion around leads.
3. Inspect Connectors for:	<ul style="list-style-type: none"> ● Loose or broken parts, cracked insulation and bad contacts.
4. Inspect Circuit Boards for:	<ul style="list-style-type: none"> ● Corrosion or damage to connectors. ● Damage to mounted components including crystals and ICs. ● Freedom from foreign material.
5. Inspect Resistors for:	<ul style="list-style-type: none"> ● Cracked, broken, charred or blistered bodies. ● Loose or corroded soldering connections.
6. Inspect Semiconductors for:	<ul style="list-style-type: none"> ● Cracked, broken, charred or discolored bodies. ● Correct placement and condition of seals around leads.
7. Inspect Wiring for:	<ul style="list-style-type: none"> ● Broken or loose ends and connections. ● Proper dress relative to other chassis parts.
	<p>NOTE: Verify wrapped wiring is tight.</p>